ABSTRACT OF THE DISCLOSURE

The present invention improves development efficiency and mass production efficiency of a semiconductor chip (LSI). The LSI on which an integrated circuit is formed has plural pad parts connecting the integrated circuit with an external circuit. The pad part is provided with the junction consisting of a window formed in the protective film and the pad exposing from the window, and the junction consisting of a window formed in the protective film and the bump deposited on the pad exposing from the window. When it is required the LSI is connected with an external circuit by wire bonding, the junction is connected with the external circuit through the wire, and when it is required to connect with an external circuit with the TAB method or the COG method, the junction is directly connected to the external circuit.

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